



SMD Comm X8G HT150C Flex, Ceramic, 620 pF, 1%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1812
L	4.5mm +/-0.4mm
W	3.2mm +/-0.3mm
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.7mm +/-0.35mm

4000

Packaging Quantity

L	4.5mm +/-0.4mm	Measurement Condition
W	3.2mm +/-0.3mm	Tolerance
Т	1mm +/-0.10mm	Voltage DC
S	2.3mm MIN	Dielectric Withstanding Voltage
В	0.7mm +/-0.35mm	Temperature Range
		Temp. Coefficient
Packaging Specifications		Capacitance Change with
Packaging	T&R, 330mm, Plastic Tape	Reference to +25°C and 0 VDC

Specifications	
Capacitance	620 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	1%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Insulation Resistance 10

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